



MOLD-TO-POSITION PRODUCT
 Minimums or set-up charges may apply. Call Samtec.

ALC-314-SGT



ALC-624-NGG

(2,54mm) .100"

ALC SERIES

ALUMINUM DIP SOCKET CARRIER

Mates with:
 APA

Aluminum Carriers for Direct Soldering to PC Boards

Samtec aluminum carriers are available in the most popular DIP lead counts for direct mounting of lead sockets to the printed circuit board.

They are ideal for vapor phase, infrared and other high temperature soldering techniques.

Low insertion force, six-finger contacts or standard insertion force four-finger contacts are available. Shell styles include ultra-low profile designs.

ALC	ROW SPACING & NO. OF CONTACTS	STYLE OPTION	PLATING OPTION	OTHER OPTION																				
Specify from chart below																								
	<table border="1"> <thead> <tr> <th>Row Space</th> <th>No. of Contacts</th> </tr> </thead> <tbody> <tr> <td>-314</td> <td>14</td> </tr> <tr> <td>-316</td> <td>16</td> </tr> <tr> <td>-318</td> <td>18</td> </tr> <tr> <td>-320</td> <td>20</td> </tr> <tr> <td>-324</td> <td>24</td> </tr> <tr> <td>-624</td> <td>24</td> </tr> <tr> <td>-628</td> <td>28</td> </tr> <tr> <td>-632</td> <td>32</td> </tr> <tr> <td>-640</td> <td>40</td> </tr> </tbody> </table>	Row Space	No. of Contacts	-314	14	-316	16	-318	18	-320	20	-324	24	-624	24	-628	28	-632	32	-640	40			
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		<p>GG = 30µ" (0,76µm) Gold Contact 10µ" (0,25µm) Gold Shell</p> <p>GT = 30µ" (0,76µm) Gold Contact, Tin Shell</p> <p>TT = Tin Contact and Shell (Styles -S, -ZS, -L, -M, -N only)</p> <p>ST = 10µ" (0,25µm) Gold Contact Tin Shell (Styles -S & -ZS only)</p>	<p>-L = Locking Socket</p> <p>Requires Style -S, -ZS, or -ZP and .035"±.003" board hole.</p> <p>Requires GT Plating Option</p> <p>Lead DIA Accepted = .015" to .022" (0,38mm to 0,56mm) Insertion Depth = .095" to .150" (2,41mm to 3,81mm) Component Part No. = SC-1L1 or EZ-1L1</p>																					

Low Insertion Force (LIF) Contacts Available.

SPECIFICATIONS

For complete specifications see www.samtec.com?ALC

Insulator Material:

None

Carrier Material:

Aluminum

Contact: BeCu

Shell: Brass

Plating:

Au over 50µ" (1,27µm) Ni

or Sn over 100µ" (2,54µm)

Cu or 50µ" (1,27µm) Ni

Current Rating:

1 A

Contact Resistance:

10 mΩ min

Insertion Force:

Standard = 9 oz (2,50N)

avg, 16 oz (4,45N) max

Low Insertion Force = 2,5 oz (0,70N) avg, 5,5 oz (1,53N) max

Withdrawal Force:

Standard = 2,5 oz (0,70N) avg,

1,5 oz (0,42N) min

Low Insertion Force = 2,0 oz (0,56N) avg, 0,35 oz (0,10N) min except Styles ZM & ZN

= 2,0 oz (0,56N) avg, 0,5 oz (0,14N) min

Note:

Some sizes, styles and options are non-standard, non-returnable.

<p>-S = Standard Solder Tail For LIF Specify -ZS</p> <p>Lead DIA Accepted = .015" to .022" (0,38mm to 0,56mm) Insertion Depth = .095" to .150" (2,41mm to 3,81mm) Style S Component Part No. = SC-1P1 Style ZS Component Part No. = EZ-1P1</p>	<p>-L = Low Profile, Hollow Leg For LIF Specify -ZL</p> <p>Lead DIA Accepted = .015" to .020" (0,38mm to 0,51mm) Insertion Depth = .105" to .170" (2,76mm to 4,32mm) Style L Component Part No. = SC-3P1 Style ZL Component Part No. = EZ-3P1</p>
<p>-M = Low Profile, Standard Mount For LIF Specify -ZM</p> <p>Lead DIA Accepted = .016" to .021" (0,41mm to 0,53mm) Insertion Depth = .080" to .115" (2,03mm to 2,92mm) Style M Component Part No. = SC-4P1 Style ZM Component Part No. = EZ-4P1</p>	<p>-N = Low Profile, Micro Socket For LIF Specify -ZN</p> <p>Lead DIA Accepted = .016" to .020" (0,41mm to 0,51mm) Insertion Depth = .080" to .150" Style N Component Part No. = SC-5P1 Style ZN Component Part No. = EZ-5P1</p>

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM